SiHG24N65E

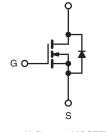
Vishay Siliconix



E Series Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	700			
R _{DS(on)} max. at 25 °C (Ω)	$V_{GS} = 10 V$	0.145		
Q _g max. (nC)	122			
Q _{gs} (nC)	21			
Q _{gd} (nC)	37			
Configuration	Single			





N-Channel MOSFET

FEATURES

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-247AC
Lead (Pb)-free	SiHG24N65E-E3
Lead (Pb)-free and Halogen-free	SiHG24N65E-GE3

ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \degree C$, unless otherwise noted)							
PARAMETER			SYMBOL	LIMIT	UNIT		
Drain-Source Voltage			V _{DS}	650	V		
Gate-Source Voltage			V _{GS}	± 30	v		
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C	- I _D	24			
	V _{GS} at 10 V	T _C = 100 °C		16	А		
Pulsed Drain Current ^a			I _{DM}	70			
Linear Derating Factor				2	W/°C		
Single Pulse Avalanche Energy ^b			E _{AS}	508	mJ		
Maximum Power Dissipation			PD	250	W		
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C		
Drain-Source Voltage Slope	T _J = 125 °C			37			
Reverse Diode dV/dt ^d		dV/dt	11	V/ns			
Soldering Recommendations (Peak Temperature) ^c	for 10 s			300	°C		

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 6 A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D$, dl/dt = 100 A/µs, starting T_J = 25 °C.

1 For technical questions, contact: <u>hvm@vishay.com</u>



COMPLIANT HALOGEN

FREE



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$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	THERMAL RESISTANCE RAT	INGS							
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	PARAMETER	SYMBOL	TYP. MAX.				UNIT		
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	Maximum Junction-to-Ambient	R _{thJA}	- 62						
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	Maximum Junction-to-Case (Drain)	R _{thJC}	- 0.5						
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$									
Static VDS VDS VDS VDS VDS Event Source Source Breakdown Voltage VDS Orain-Source Dreshold Voltage (N) VDS PVDS PVDS PVDS PUSD	SPECIFICATIONS (T _J = 25 $^{\circ}$ C, u	unless otherwi	se noted)						
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT
	Static								
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D =	250 µA	650	-	-	V
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C,	I _D = 250 μΑ	-	0.72	-	V/°C
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D =	250 µA	2	-	4	V
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Cato Source Leakage	1	V _{GS} = ± 20 V		V	-	-	± 100	nA
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate-Source Leakage	IGSS	$V_{GS} = \pm 30 \text{ V}$			-	-	± 1	μA
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	Zero Gate Voltage Drain Current	Inco	V _{DS} = 650 V, V _{GS} = 0 V		_{as} = 0 V	-	-	1	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Zero Gate Voltage Drain Current	USS	V _{DS} = 520 \	$V_{DS} = 520 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$		-	-	10	μΑ
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$		_D = 12 A	-	0.120	0.145	Ω
$\begin{array}{ c c c c c c } \hline Input Capacitance & C_{iss} & V_{GS} = 0 \ V, \\ V_{DS} = 100 \ V, \\ T = 1 \ MHz & - & PF \\ \hline \\ \hline \\ \hline \\ \hline \\ Peterse Transfer Capacitance & C_{rss} & f = 1 \ MHz & - & 122 & - & PF \\ \hline \\ \hline \\ \hline \\ Peterse Transfer Capacitance, Energy \\ Related ^{a} & C_{o(er)} & V_{DS} = 0 \ V \ to \ 520 \ V, \ V_{GS} = 0 \ V \\ \hline \\ \hline \\ \hline \\ Peterse Coutput Capacitance, Time \\ Related ^{b} & C_{o(tr)} & V_{DS} = 0 \ V \ to \ 520 \ V, \ V_{GS} = 0 \ V \\ \hline \\$	Forward Transconductance	9 _{fs}	$V_{DS} = 8 V, I_D = 5 A$		-	7.1	-	S	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Dynamic					-		-	•
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Input Capacitance	C _{iss}		$V_{GS} = 0$	/.	-	2740	-	pF
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Output Capacitance	C _{oss}	$V_{DS} = 100 V,$		-	122	-		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Reverse Transfer Capacitance	C _{rss}		f = 1 MHz		-	4	-	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Effective Output Capacitance, Energy Related ^a	C _{o(er)}	$V_{\rm DS}$ = 0 V to 520 V, $V_{\rm GS}$ = 0 V		-	93	-		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	352	-		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Total Gate Charge	Qg				-	81	122	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate-Source Charge	Q _{gs}	V _{GS} = 10 V I _D = 12 A,		A, V _{DS} = 520 V	-	21	-	nC
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate-Drain Charge	Q _{gd}				-	37	-	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Turn-On Delay Time	t _{d(on)}				-	24	48	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Rise Time		V _{DD} =	= 520 V. In	= 12 A.	-	84	126	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Turn-Off Delay Time	t _{d(off)}	$V_{\rm BD} = 320$ V, $T_{\rm D} = 12$ A, $V_{\rm GS} = 10$ V, $R_{\rm q} = 9.1$ Ω		-	70	105	115	
Drain-Source Body Diode CharacteristicsContinuous Source-Drain Diode CurrentIsMOSFET symbol showing the integral reverse p - n junction diode-24APulsed Diode Forward CurrentIsMIsM $r_{J} = 25 \ ^{\circ}C$, Is = 12 A, VGS = 0 V70ADiode Forward VoltageVSDTJ = 25 \ ^{\circ}C, Is = 12 A, VGS = 0 V1.2VReverse Recovery TimetrrTJ = 25 \ ^{\circ}C, IF = IS = 12 A, dl/dt = 100 A/µs, VB = 25 V433-ns	Fall Time	t _f		g		-	69	104	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate Input Resistance	R _g	f = 1 MHz, open drain		-	0.68	-	Ω	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Drain-Source Body Diode Characteristi	cs							
Pulsed Diode Forward CurrentIsmIntegral reverse p - n junction diode70Diode Forward Voltage V_{SD} $T_J = 25 \ ^{\circ}C$, $I_S = 12 \ A$, $V_{GS} = 0 \ V$ 1.2VReverse Recovery Time t_{rr} $T_J = 25 \ ^{\circ}C$, $I_F = I_S = 12 \ A$, dl/dt = 100 A/µs, $V_R = 25 \ V$ 433-ns	Continuous Source-Drain Diode Current	١ _S	showing the integral reverse		-	-	24		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Pulsed Diode Forward Current	I _{SM}			-	-	70	A	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 12 A, V _{GS} = 0 V		-	-	1.2	V	
Reverse Recovery Charge Q_{rr} $T_J = 25 \ ^{\circ}C$, $I_F = I_S = 12 \ A$, $dI/dt = 100 \ A/\mu s$, $V_R = 25 \ V$ -7.3- μC	Reverse Recovery Time		T _J = 25 °C, I _F = I _S = 12 A,		-	433	-	ns	
di/dl = 100 A/µs, v _R = 25 V	Reverse Recovery Charge				-	7.3	-	-	
	Reverse Recovery Current	-			-	28	-		

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



SiHG24N65E

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

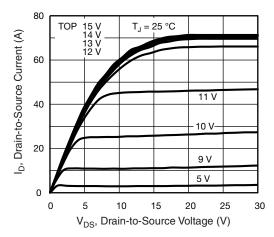


Fig. 1 - Typical Output Characteristics

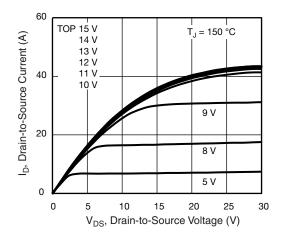


Fig. 2 - Typical Output Characteristics

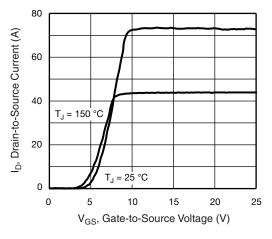


Fig. 3 - Typical Transfer Characteristics

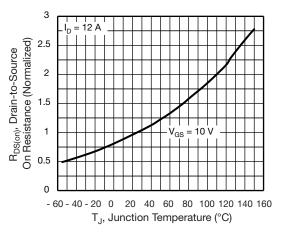


Fig. 4 - Normalized On-Resistance vs. Temperature

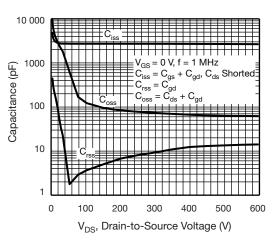
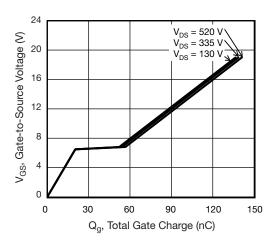


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage





S15-0291-Rev. G, 23-Feb-15

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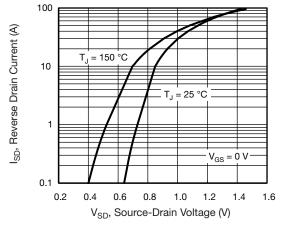


Fig. 7 - Typical Source-Drain Diode Forward Voltage

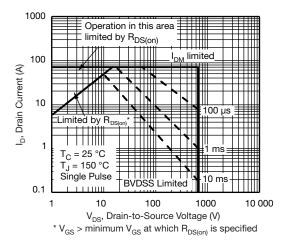


Fig. 8 - Maximum Safe Operating Area

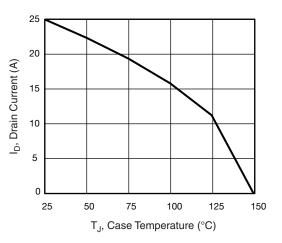


Fig. 9 - Maximum Drain Current vs. Case Temperature

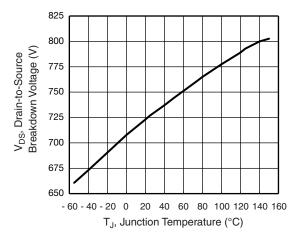
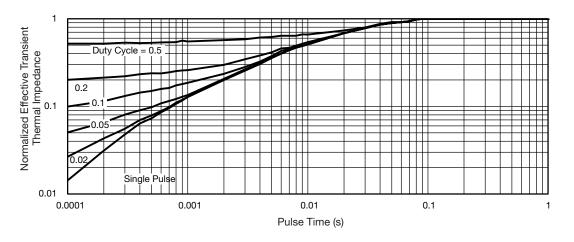


Fig. 10 - Temperature vs. Drain-to-Source Voltage





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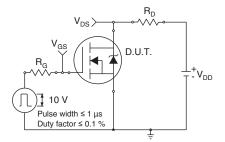


Fig. 12 - Switching Time Test Circuit

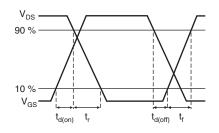


Fig. 13 - Switching Time Waveforms

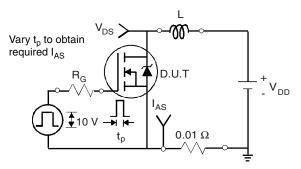


Fig. 14 - Unclamped Inductive Test Circuit

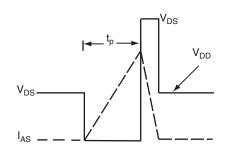


Fig. 15 - Unclamped Inductive Waveforms

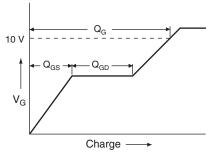


Fig. 16 - Basic Gate Charge Waveform

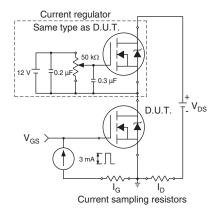


Fig. 17 - Gate Charge Test Circuit

5

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Peak Diode Recovery dV/dt Test Circuit

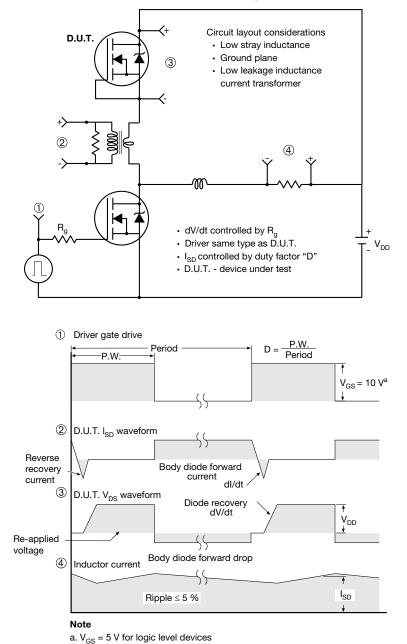


Fig. 18 - For N-Channel

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TO-247AC (High Voltage)

ECN: X13-0103-Rev. D, 01-Jul-13 DWG: 5971

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.

2. Contour of slot optional.

 Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body.

4. Thermal pad contour optional with dimensions D1 and E1.

5. Lead finish uncontrolled in L1.

6. Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154").

7. Outline conforms to JEDEC outline TO-247 with exception of dimension c.

8. Xian and Mingxin actually photo.





Vishay

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